



# PSMN017-30KL

N-channel 30 V 17 mΩ logic-level MOSFET in SO8

Rev. 01 — 14 April 2011

Objective data sheet

## 1. Product profile

### 1.1 General description

Logic level N-channel enhancement mode MOSFET in SO8 package qualified to 150 °C. This product is designed and qualified for use in a wide range of industrial, communications and power supply equipment

### 1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- High performance replacement for legacy SO8 designs
- Suitable for logic-level gate drive
- Suitable for wave and reflow soldering

### 1.3 Applications

- DC-to-DC converters
- Load switching
- Portable equipment

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 150\text{ °C}$	-	-	30	V
$I_D$	drain current	$T_{mb} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; see <a href="#">Figure 1</a>	-	-	10	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>	-	-	3	W
$T_j$	junction temperature		-55	-	150	°C

#### Static characteristics

$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 12</a>	-	20.5	25	mΩ
		$V_{GS} = 10\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 12</a>	-	15	17	mΩ

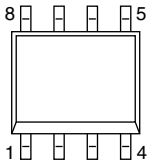
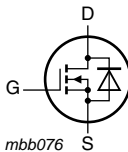


**Table 1. Quick reference data ...continued**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$V_{GS} = 10\text{ V}; I_D = 5\text{ A};$	-	1.6	-	nC
$Q_{G(\text{tot})}$	total gate charge	$V_{DS} = 15\text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	9	-	nC
		$V_{GS} = 4.5\text{ V}; I_D = 5\text{ A};$ $V_{DS} = 15\text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	4.4	-	nC
<b>Avalanche ruggedness</b>						
$E_{DS(\text{AL})S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}; T_{j(\text{init})} = 25\text{ °C};$ $I_D = 10\text{ A}; V_{\text{sup}} \leq 30\text{ V};$ unclamped; $R_{GS} = 50\text{ }\Omega$	-	-	26	mJ

## 2. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p><b>SOT96-1 (SO8)</b></p>	 <p><i>mbb076</i></p>
2	S	source		
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain		
7	D	drain		
8	D	drain		

## 3. Ordering information

**Table 3. Ordering information**

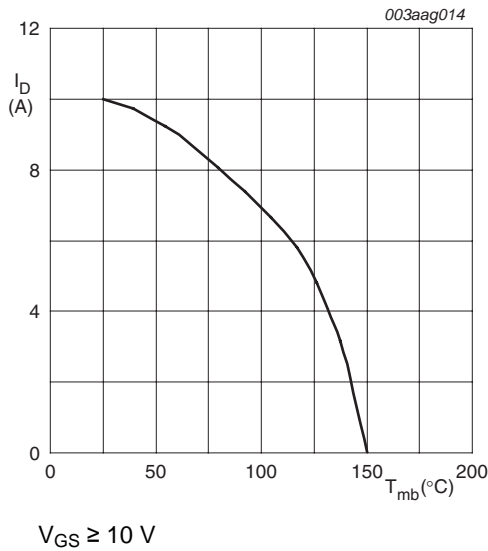
Type number	Package		Version
	Name	Description	
PSMN017-30KL	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

### 4. Limiting values

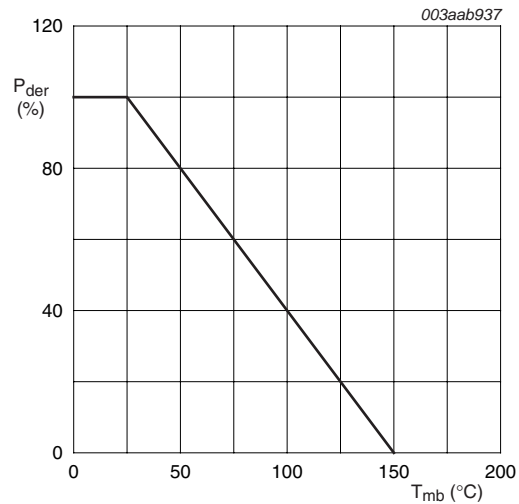
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 150 °C	-	30	V
V <sub>DGR</sub>	drain-gate voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 150 °C; R <sub>GS</sub> = 20 kΩ	-	30	V
V <sub>GS</sub>	gate-source voltage		-20	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; see <a href="#">Figure 1</a>	-	7	A
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; see <a href="#">Figure 1</a>	-	10	A
I <sub>DM</sub>	peak drain current	pulsed; t <sub>p</sub> ≤ 10 μs; T <sub>mb</sub> = 25 °C; see <a href="#">Figure 3</a>	-	40	A
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <a href="#">Figure 2</a>	-	3	W
T <sub>stg</sub>	storage temperature		-55	150	°C
T <sub>j</sub>	junction temperature		-55	150	°C
T <sub>sld(M)</sub>	peak soldering temperature		-	260	°C
<b>Source-drain diode</b>					
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	-	10	A
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 μs; T <sub>mb</sub> = 25 °C	-	40	A
<b>Avalanche ruggedness</b>					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; I <sub>D</sub> = 10 A; V <sub>sup</sub> ≤ 30 V; unclamped; R <sub>GS</sub> = 50 Ω	-	26	mJ

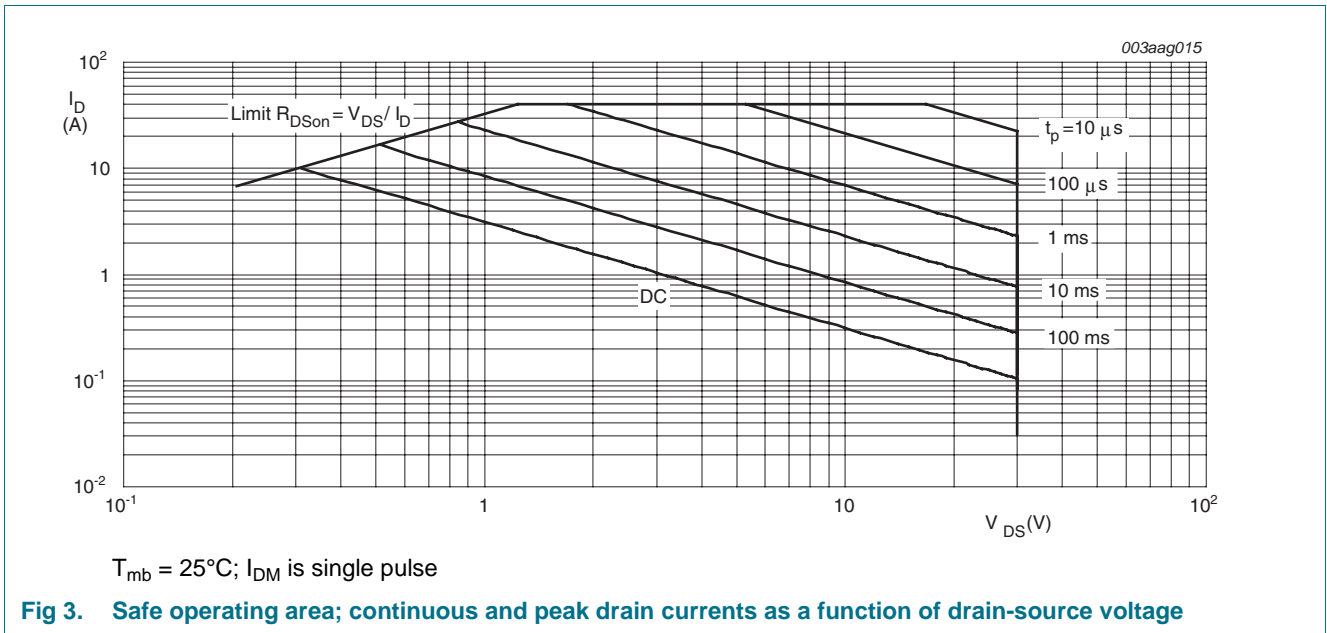


**Fig 1. Continuous drain current as a function of mounting base temperature**



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100\%$$

**Fig 2. Normalized total power dissipation as a function of solder point temperature**



### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	see <a href="#">Figure 4</a>	-	30	40	K/W

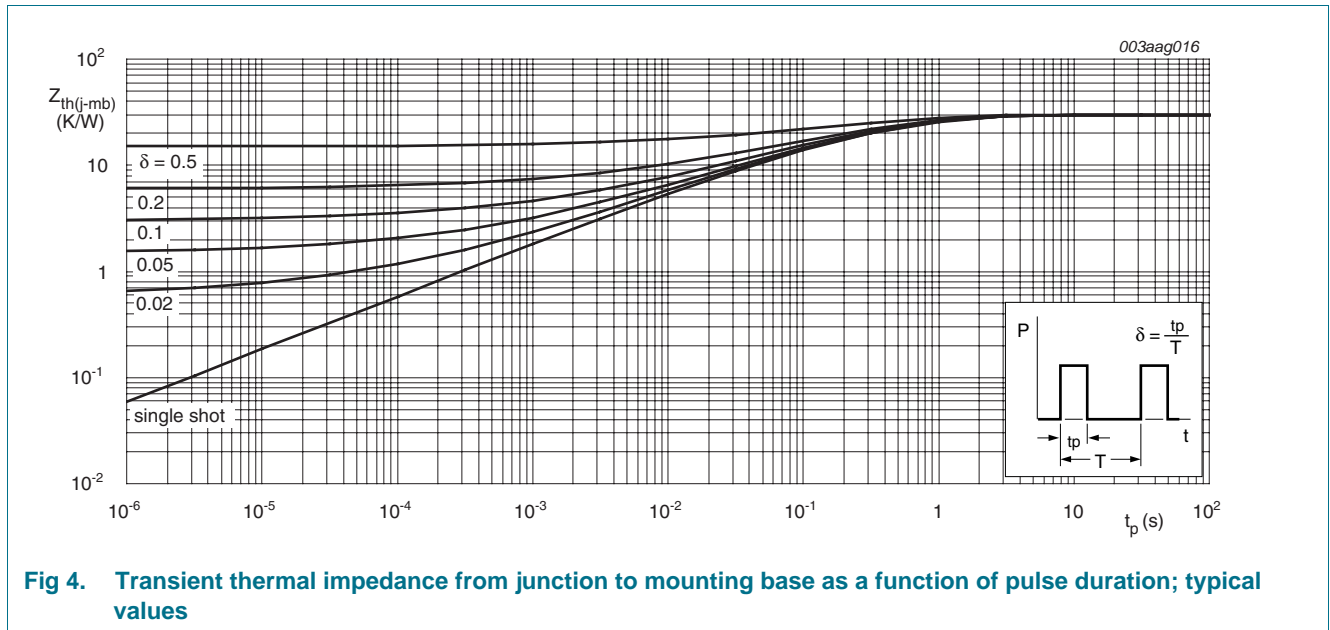


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration; typical values

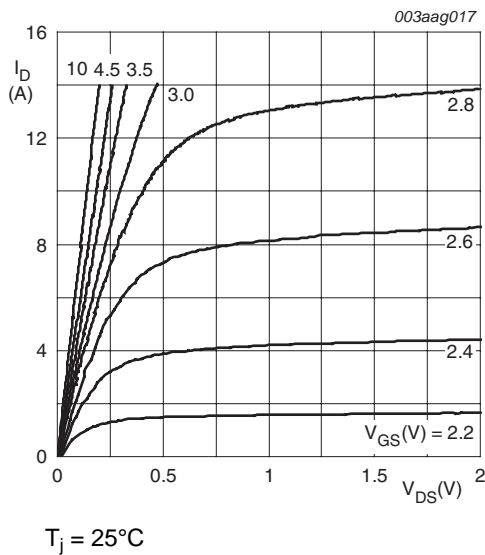
## 6. Characteristics

**Table 6. Characteristics**
*Tested to JEDEC standards where applicable.*

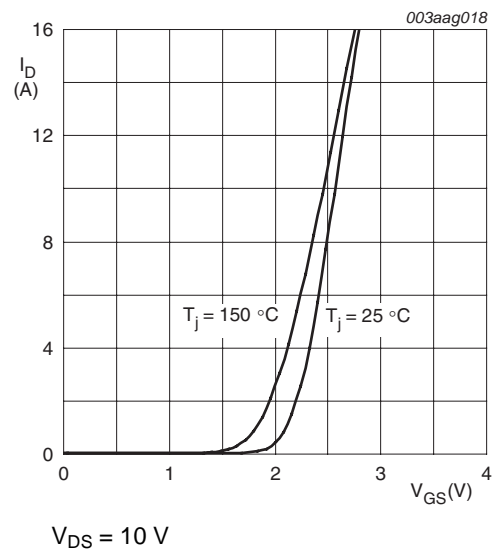
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$	27	-	-	V
		$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	30	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ see <a href="#">Figure 10</a> ; see <a href="#">Figure 11</a>	1.3	1.7	2.15	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ see <a href="#">Figure 11</a>	-	-	2.55	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ\text{C};$ see <a href="#">Figure 11</a>	0.5	-	-	V
$I_{DSS}$	drain leakage current	$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	0.1	1	$\mu\text{A}$
		$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 \text{ }^\circ\text{C}$	-	-	50	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	100	nA
		$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ see <a href="#">Figure 12</a>	-	20.5	25	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 5 \text{ A}; T_j = 100 \text{ }^\circ\text{C};$ see <a href="#">Figure 13</a> ; see <a href="#">Figure 12</a>	-	-	23	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 5 \text{ A}; T_j = 150 \text{ }^\circ\text{C};$ see <a href="#">Figure 13</a> ; see <a href="#">Figure 12</a>	-	27	30.6	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ see <a href="#">Figure 12</a>	-	15	17	mΩ
$R_G$	internal gate resistance (AC)	$f = 1 \text{ MHz}$	-	1.13	-	Ω
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 5 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 10 \text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	9	-	nC
		$I_D = 5 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 4.5 \text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	4.4	-	nC
		$I_D = 0 \text{ A}; V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}$	-	7.9	-	nC
$Q_{GS}$	gate-source charge	$I_D = 5 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 10 \text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	1.1	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	0.85	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	0.25	-	nC
$Q_{GD}$	gate-drain charge		-	1.6	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 5 \text{ A}; V_{DS} = 15 \text{ V};$ see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	2.45	-	V
$C_{iss}$	input capacitance	$V_{DS} = 15 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ\text{C};$ see <a href="#">Figure 16</a>	-	533	-	pF
$C_{oss}$	output capacitance		-	107	-	pF
$C_{rss}$	reverse transfer capacitance		-	53	-	pF

**Table 6. Characteristics ...continued**  
 Tested to JEDEC standards where applicable.

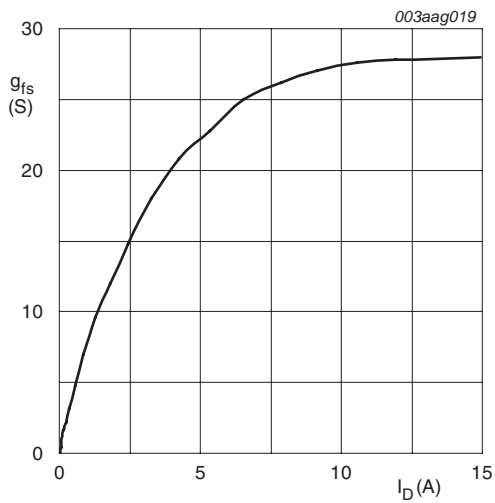
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15\text{ V}; R_L = 0.5\ \Omega; V_{GS} = 4.5\text{ V};$	-	12	-	ns
$t_r$	rise time	$R_{G(ext)} = 4.7\ \Omega; T_j = 25\text{ }^\circ\text{C}$	-	8	-	ns
$t_{d(off)}$	turn-off delay time		-	12	-	ns
$t_f$	fall time		-	4	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 5\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ see <a href="#">Figure 17</a>	-	0.82	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 5\text{ A}; dI_S/dt = 100\text{ A}/\mu\text{s};$	-	16	-	ns
$Q_r$	recovered charge	$V_{GS} = 0\text{ V}; V_{DS} = 15\text{ V}$	-	9	-	nC



**Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values**

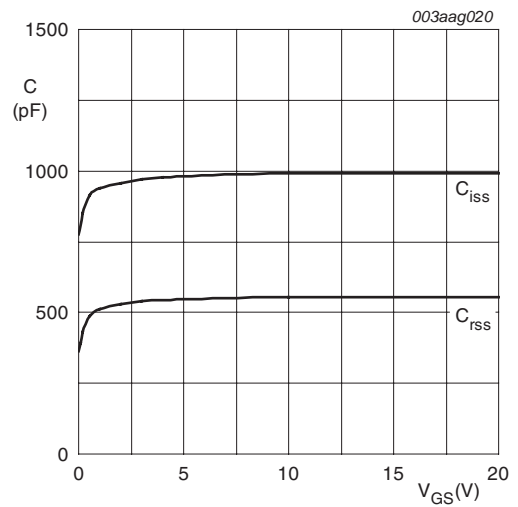


**Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



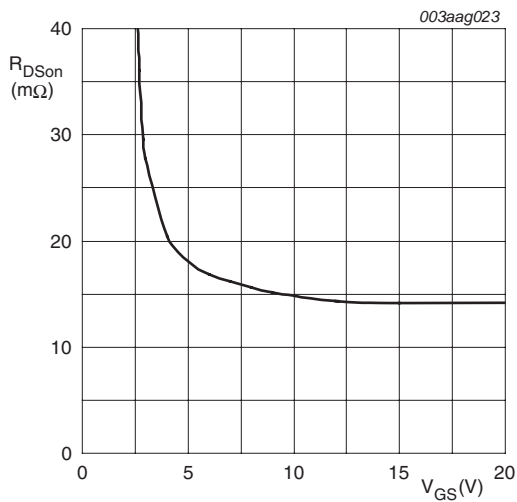
$T_j = 25^\circ\text{C}; V_{DS} = 10\text{ V}$

Fig 7. Forward transconductance as a function of drain current; typical values



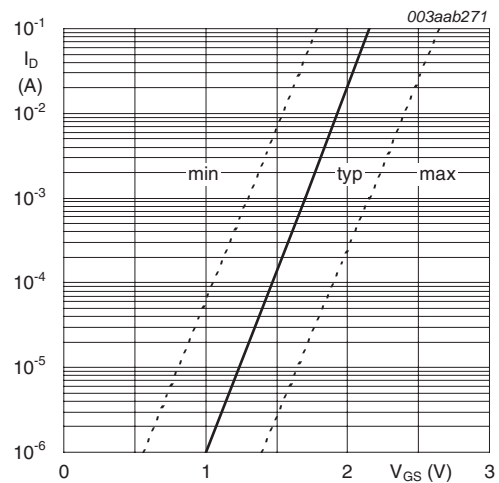
$V_{DS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 8. Input and reverse transfer capacitances as a function of gate-source voltage; typical values



$T_j = 25^\circ\text{C}; I_D = 5\text{ A}$

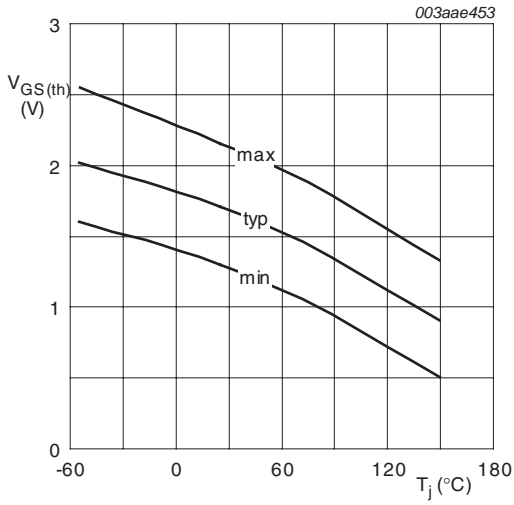
Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



$T_j = 25^\circ\text{C}; V_{DS} = 5\text{ V}$

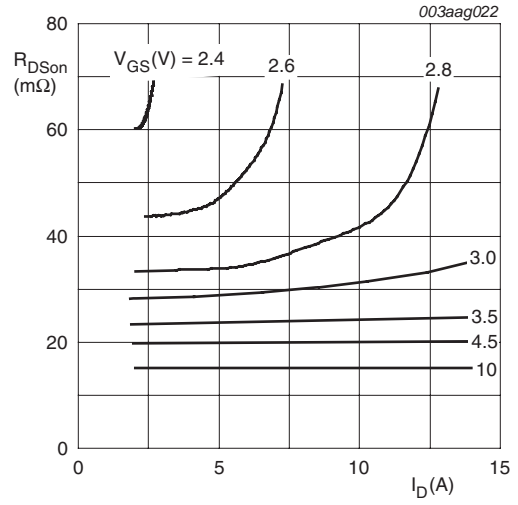
Fig 10. Sub-threshold drain current as a function of gate-source voltage





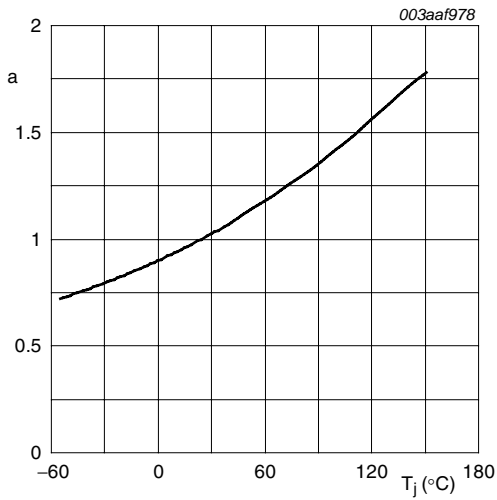
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

**Fig 11. Gate-source threshold voltage as a function of junction temperature**



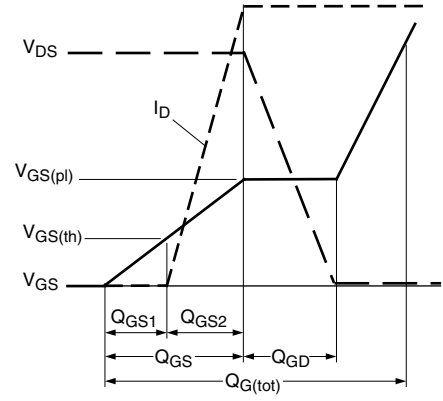
$T_j = 25^\circ\text{C}$

**Fig 12. Drain-source on-state resistance as a function of drain current; typical values**



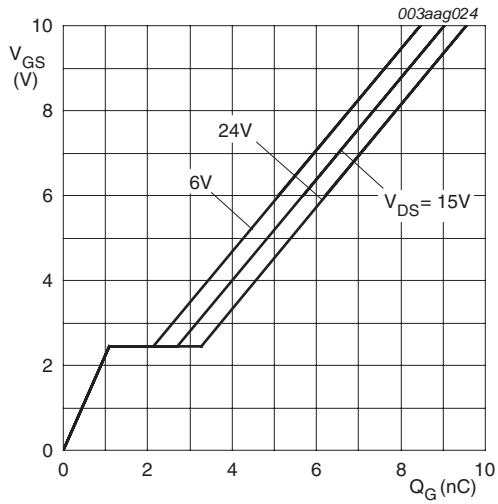
$$a = \frac{R_{DS(on)}}{R_{DS(on)25^\circ\text{C}}}$$

**Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature**



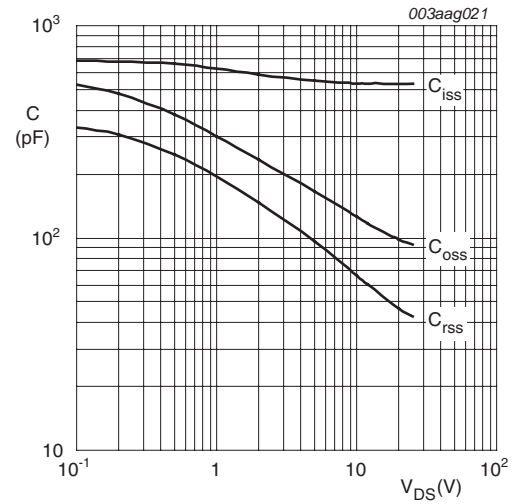
003aaa508

**Fig 14. Gate charge waveform definitions**



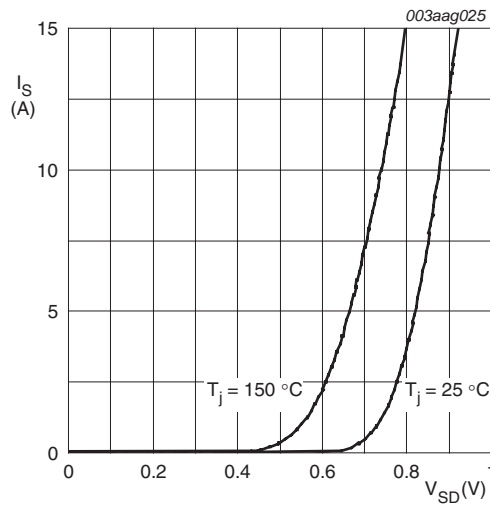
$T_j = 25^\circ\text{C}$  and  $I_D = 5\text{ A}$

Fig 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}$ ,  $f = 1\text{ MHz}$

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0\text{ V}$

Fig 17. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

7. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1

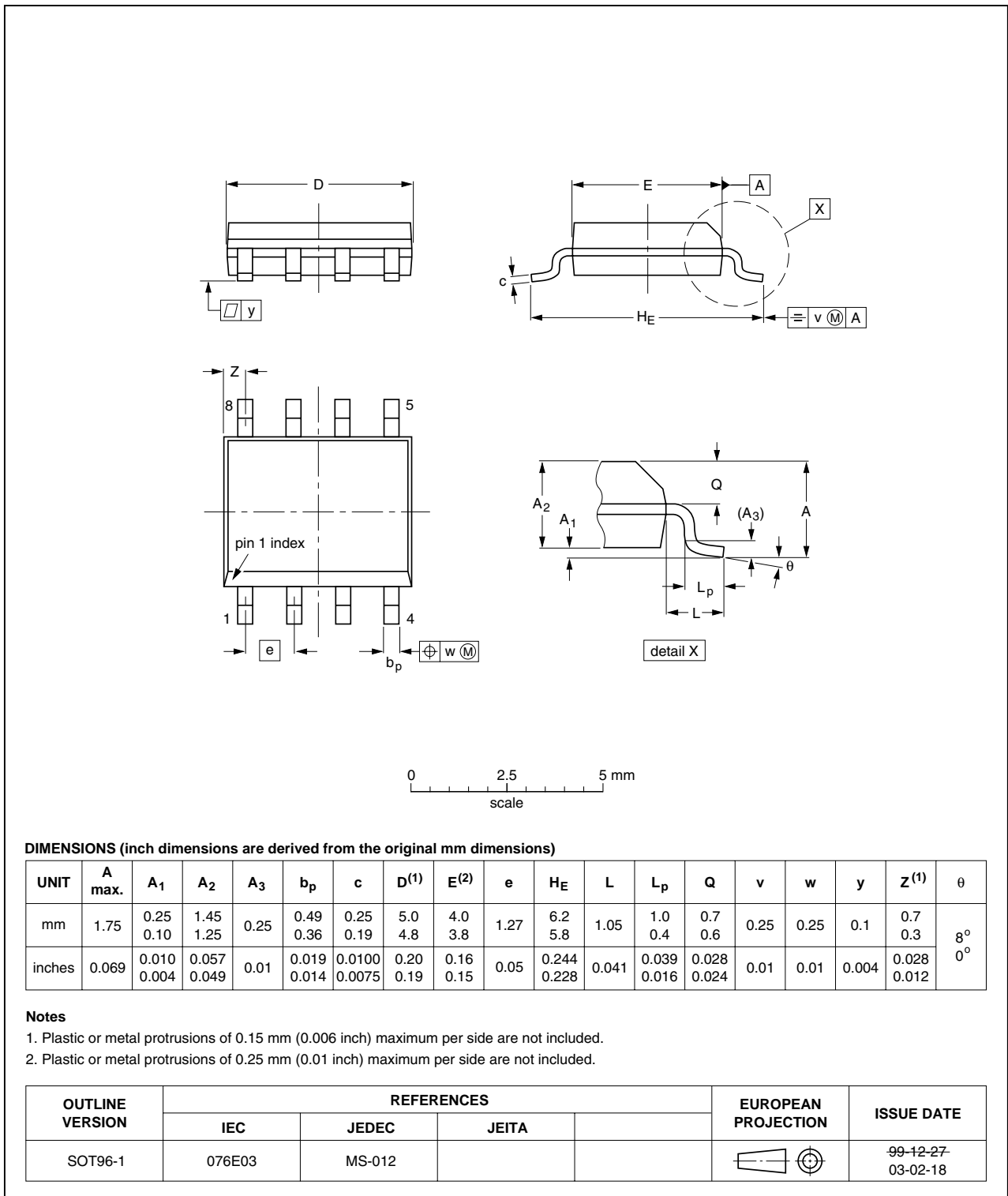


Fig 18. Package outline SOT96-1 (SO8)

## 8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN017-30KL v.1	20110414	Objective data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1]</sup> <sup>[2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## 11. Contents

<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Limiting values</b> . . . . .	<b>3</b>
<b>5</b>	<b>Thermal characteristics</b> . . . . .	<b>5</b>
<b>6</b>	<b>Characteristics</b> . . . . .	<b>6</b>
<b>7</b>	<b>Package outline</b> . . . . .	<b>11</b>
<b>8</b>	<b>Revision history</b> . . . . .	<b>12</b>
<b>9</b>	<b>Legal information</b> . . . . .	<b>13</b>
9.1	Data sheet status . . . . .	13
9.2	Definitions . . . . .	13
9.3	Disclaimers . . . . .	13
9.4	Trademarks . . . . .	14
<b>10</b>	<b>Contact information</b> . . . . .	<b>14</b>

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